ABSOLUTE MAXIMUM RATINGS

PS, LX, OUT to GND	0.3V to +11.5V	Continuous Power Dissipation ($T_A = +70$ °C)	
ILIM, SHDN, STBY, FB, 3/5, N/E, LBO,		SO (derate 8.70mW/°C above +70°C)	
LBI-, LBI+, REF to GND	0.3V to (V _{PS} + 0.3V)	Operating Temperature Range	40°C to +85°C
PGND to GND	0.3V to +0.3V	Storage Temperature Range	65°C to +160°C
REF Short Circuit to GND	Continuous	Junction Temperature	+150°C
lout	700mA	Lead Temperature (soldering, 10sec)	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{PS} = 5.6V, \overline{STBY} = PS, C_{REF} = 0.1 \mu F, C_{OUT} = 4.7 \mu F, T_{A} = -40 ^{\circ}C$ to $+85 ^{\circ}C$, unless otherwise noted. Typical values are at $T_{A} = +25 ^{\circ}C$.) (Note 1)

PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
Input Valtage	N/E = PS		1.8		11.0	V
Input Voltage	N/E = GND (Note 2)		1.8		7.0	
Full Load Start-Up Voltage				0.9		V
	$3\overline{/5} = low,$	$T_A = 0$ °C to +85°C	4.8	5.0	5.2	
Output Voltage (MAX710)	$I_{OUT} = 0$ to 250mA	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	4.6	5.0	5.3	1
Output voltage (MAX7 10)	$3/\overline{5}$ = high, I_{OUT} = 0 to	$T_A = 0$ °C to +85°C	3.17	3.3	3.43	V
	250mA, Vps = 4.7V	$T_A = -40$ °C to $+85$ °C	3.05	3.3	3.55	
Output Voltage-Adjustment Range	MAX711	•	FB		5.5	V
Output Voltage Load Regulation	0 < I _{OUT} < 250mA, STBY =	= PS		0.5		%
Output Voltage Line Regulation	STBY = PS, 1.8V to 5V			0.3		%/V
Quiescent Current	$V_{\overline{STBY}} = V_{\overline{SHDN}} = \text{logic hi}$ into PS pin; $I_{LOAD} = 0$	VSTBY = VSHDN = logic high, current measured into PS pin; ILOAD = 0		100	140	μА
Standby Quiescent Current	V _{STBY} = 0V			7	16	μΑ
Shutdown Quiescent Current	VSHDN = 0V			0.1	5	μΑ
Reference Voltage	$T_A = 0$ °C to +85°C, $I_{REF} = 0$		1.24	1.28	1.31	V
Thereferice voltage	$T_A = -40$ °C to $+85$ °C, $I_{REF} = 0$		1.23	1.28	1.32	ľ
Standby Output Current	VSTBY = 0V, linear regulate	or			10	mA
FB Voltage	MAX711, OUT = FB	$T_A = 0$ °C to +85°C	1.20	1.25	1.29	mV
T b voltage	WAXIII, OOI = I B	$T_A = -40$ °C to $+85$ °C	1.18	1.25	1.31	1110
Load Regulation	MAX711, OUT = FB	MAX711, OUT = FB		0.1	1	%
FB Input Current	FB = 1.25V			1	50	nA
	V _{PS} = 5.6V			0.2	0.6	
LX On-Resistance	MAX710, V _{PS} = 3.7V			0.3	0.9	Ω
	MAX711, Vps = 2.7V			0.6	1.2	
LX Leakage Current	V _{LX} = 5.6V			0.1	1	μΑ
LX Current Limit	ILIM = PS		0.5	0.8	1.3	A
EX Guirgitt Elithit	ILIM = GND		1.1	1.5	1.95	

ELECTRICAL CHARACTERISTICS (continued)

(VPS = 5.6V, \overline{STBY} = PS, C_{REF} = 0.1 μ F, C_{OUT} = 4.7 μ F, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A = +25°C.) (Note 1)

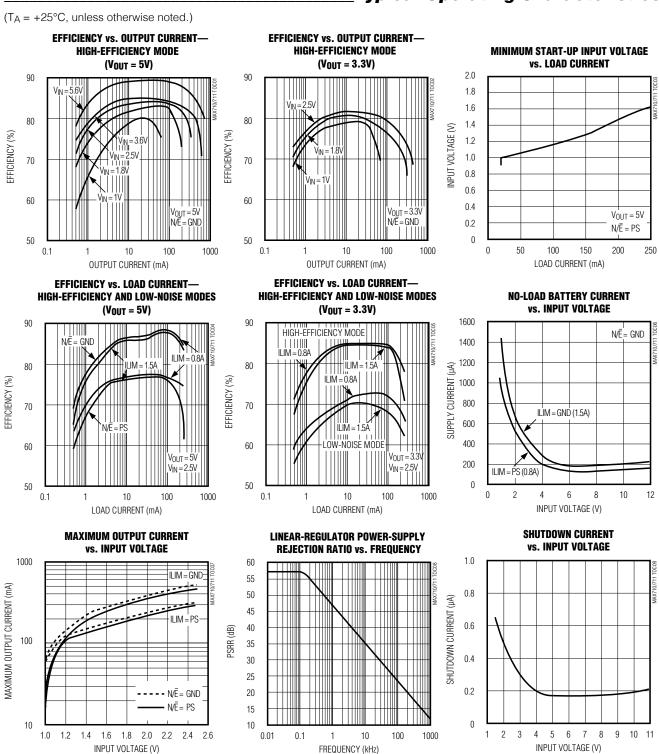
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
	V _{OUT} = 5.0V		0.7	1.3		
Output PFET Resistance	MAX710, V _{OUT} = 3.0V		1.3	2.4	Ω	
	MAX711, V _{OUT} = 2.7V		1.6	3.0		
Output PFET Leakage	V _{PS} = 3V, V _{OUT} = 0V		0.4	3	μΑ	
Thermal Shutdown	STBY = PS		150		°C	
Thermal Shutdown Hysteresis	STBY = PS		20		°C	
LOGIC						
Input Low Voltage	STBY, SHDN, N/E, 3/5, ILIM			0.4	V	
Input High Voltage	STBY, SHDN, N/E, 3/5, ILIM	1.6			V	
Input Bias Current	STBY, SHDN, N/E, 3/5, ILIM		1	50	nA	
LBI/LBO COMPARATOR		•				
Input Range LBI-, LBI+	(Note 3)	1.2		10	V	
Input Bias Current LBI-, LBI+	V _{LBI-} , V _{LBI+} = 1.25V		1	50	nA	
Hysteresis		6	40	100	mV	
LBI/LBO Offset Voltage	V _{LBI-} = 1.25V	-25		+25	mV	
L DO Outrout Voltage	$I_{LBO} = 2mA, V_{LBI-} = 1.25V, V_{LBI+} = 1V$			0.4	V	
LBO Output Voltage	$I_{LBO} = -300\mu A$, $V_{LBI-} = 1.25V$, $V_{LBI+} = 2V$	Vps - 0.2	V			

Note 1: Specifications at -40°C are guaranteed by design, not production tested.

Note 2: Guaranteed by design (see Table 1).

Note 3: The LBO comparator provides the correct result as long as one input is within the specified input range.

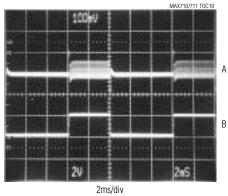
Typical Operating Characteristics



Typical Operating Characteristics (continued)

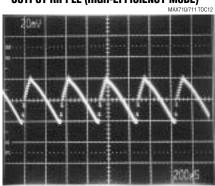
 $(T_A = +25$ °C, unless otherwise noted.)

LINE-TRANSIENT RESPONSE



A: $V_{OUT} = 3.3V$ (100mV/div, AC COUPLED), N/ \overline{E} = GND B: $V_{IN} = 2V$ TO 4V, $I_{OUT} = 100$ mA

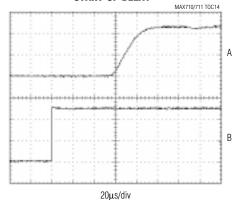
OUTPUT RIPPLE (HIGH-EFFICIENCY MODE)



 V_{IN} = 2.5V, I_{OUT} = 20mA, N/\bar{E} = GND V_{OUT} = 5V (20mV/div, AC COUPLED), I_{OUT} = 20mA

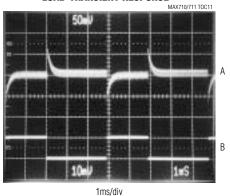
START-UP DELAY

200µs/div



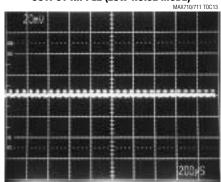
A: V_{OUT} (2V/div), I_{OUT} = 100mA B: V_{SHDN} (2V/div)

LOAD-TRANSIENT RESPONSE



A: $V_{OUT} = 3.3V$ (50mV/div, AC COUPLED), $N/\overline{E} = PS$ B: $I_{OUT} = 10$ mA TO 100mA

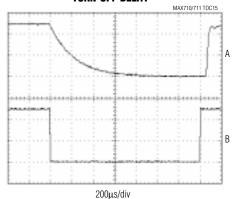
OUTPUT RIPPLE (LOW-NOISE MODE)



 V_{IN} = 2.5V, I_{OUT} = 20mA, N/E = PS V_{OUT} = 5V (20mV/div, AC COUPLED), I_{OUT} = 20mA

TURN-OFF DELAY

200µs/div



A: V_{OUT} (2V/div), $I_{OUT} = 100$ mA B: $V_{\overline{SHDN}}$ (2V/div)

Pin Description

PIN		NAME	FUNCTION	
MAX710	MAX711	NAME	FUNCTION	
1	1	LX	Drain Connection for internal N-channel power MOSFET	
2	2	PGND	Power Ground	
3	3	ILIM	Inductor Current-Limit-Select Input. Connect to GND for 1.5A limit and to PS for 0.8A limit.	
4	4	SHDN	Shutdown Input. When low, the entire circuit is off and OUT is actively pulled to GND.	
5	5	STBY	Standby Input. Connect to GND to disable boost circuit. Connect to PS for normal operation.	
6	_	3/5	Selects the output voltage. Connect to GND for 5V output and to OUT for 3.3V output.	
_	6	FB	Feedback Input	
7	7	N/Ē	Selects low-noise or high-efficiency mode. Connect to GND for high efficiency and to PS for lowest noise. See <i>Operating Configurations</i> section.	
8	8	LBO	Low-Battery Comparator Output	
9	9	OUT	Linear-Regulator Output. Bypass with a 4.7µF capacitor to GND.	
10	10	LBI-	Negative Input to Low-Battery Comparator	
11	11	LBI+	Positive Input to Low-Battery Comparator	
12	12	PS	Source of internal PFET regulator. The IC is powered from PS.	
13	13	REF	1.28V Reference Voltage Output. Bypass with a 0.1µF capacitor to GND.	
14	14	GND	Analog Ground. Must be low impedance. Solder directly to ground plane.	
15	15	PGND	Power Ground	
16	16	LX	Drain Connection for internal N-channel power MOSFET	

Detailed Description

The MAX710/MAX711 integrate a step-up DC-DC converter with a linear regulator to provide step-up/down voltage conversion. The step-up switch-mode regulator contains an N-channel power MOSFET switch. It also shares a precision voltage reference with a linear regulator that contains a P-channel MOSFET pass element (Figure 1).

Step-Up Operation

A pulse-frequency-modulation (PFM) control scheme with a constant 1µs off-time and variable on-time controls the N-channel MOSFET switch. The N-channel switch turns off when the part reaches the peak current limit or the 4µs maximum on-time. The ripple frequency is a function of load current and input voltage.

Step-Down Operation

The low-dropout linear regulator consists of a reference, an error amplifier, and a P-channel MOSFET. The reference is connected to the error amplifier's inverting

input. The error amplifier compares this reference with the selected feedback voltage and amplifies the difference. The difference is conditioned and applied to the P-channel pass transistor's gate.

Operating Configurations

The MAX710/MAX711 have several operating configurations to minimize noise and optimize efficiency for different input voltage ranges. These configurations are accomplished via the N/E input, which controls operation of the on-chip linear regulator.

With N/ \overline{E} low, the linear regulator behaves as a 0.7 Ω (at 5V output) PFET switch when the IC is boosting, and as a conventional linear regulator when V_{IN} > V_{OUT}. This provides optimum boost efficiency, but the PFET does little to reject boost-converter output ripple. With N/ \overline{E} high, boost ripple rejection is optimized by maintaining headroom (V_{FV}, typically 0.5V at 5V output) across the linear regulator. Boost mode efficiency is then about 10% lower than with N/ \overline{E} high.

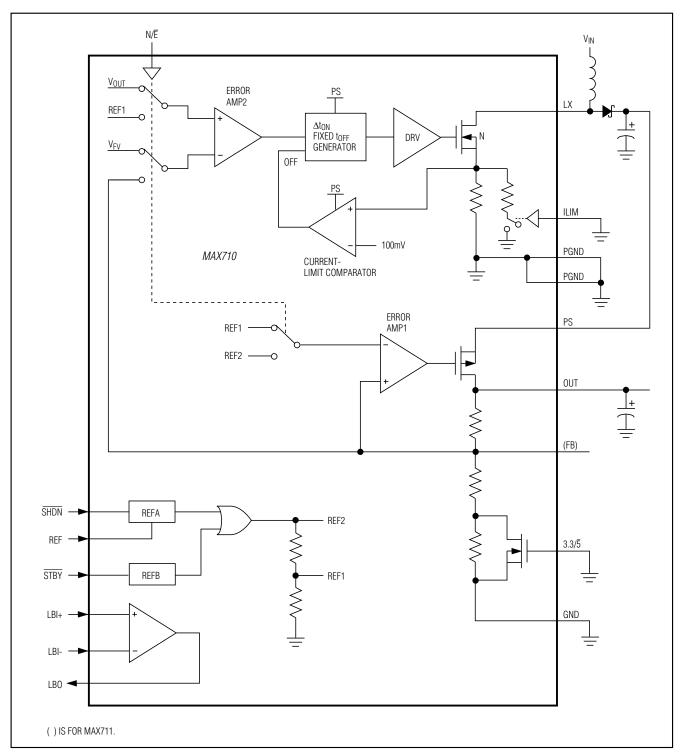


Figure 1. Functional Diagram

In high-efficiency mode (N/E = low), the maximum input voltage is limited to 7V. This voltage limitation is easily overcome, however, by configuring the LBO output to change modes based on input voltage, allowing an 11V maximum input with high-efficiency configurations. Four operating configurations are described in Table 1 and in the following subsections.

Table 1. Operating Configurations

NO.	DESCRIPTION	INPUT VOLTAGE	CONNECTIONS
1	High efficiency, 7V max V _{IN}	Up to 7V	N/E = GND
2	High efficiency, VBATT < VOUT (Figure 2a)	Up to 11V	LBO = N/E LBI- = VOUT LBI+ = VIN
3	High efficiency, 11V, V _{BATT} < 6.5V (Figure 2b)	Up to 11V	LBO = N/E LBI- = REF LBI+ = R5, R6
4	Low noise	Up to 11V	$N/\overline{E} = PS$

Configuration 1: High Efficiency, 7V Max V_{IN} With N/E connected to GND, when the IC boosts, the linear regulator operates only as a switch, with minimum forward drop, until $V_{IN} > V_{OUT}$ (where linear regulation begins). This configuration is limited to no more than 7V input, but provides best efficiency for battery-only operation or low-voltage AC adapter usage.

Configuration 2: High Efficiency, $V_{BATT} < V_{OUT}$ In this configuration, N/\overline{E} is driven high by LBO when $V_{IN} > V_{OUT}$ (Figure 2a). When $V_{IN} < V_{OUT}$, the IC boosts, and the linear regulator operates as a switch, with minimum forward drop. When $V_{IN} > V_{OUT}$, the linear regulator operates with V_{FV} forward drop, while V_{PS} increases by V_{FV} so that OUT maintains regulation. V_{FV} is set inside the IC to approximately 0.5V (at 5V V_{OUT}). When V_{IN} is only slightly higher than V_{OUT} , conversion efficiency is poorer than in configuration 1, so configuration 2 is most suitable when the battery voltage is less than V_{OUT} , but the AC adapter output is greater than V_{OUT} .

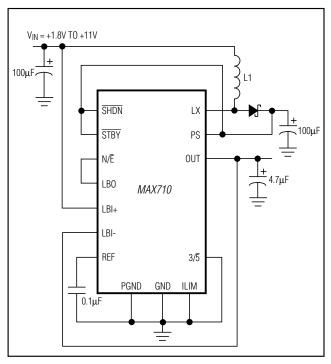


Figure 2a. High-Efficiency Operating Configuration for VBATT < VOUT

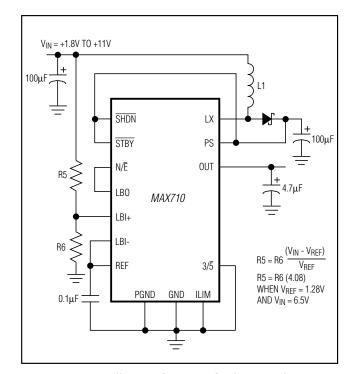


Figure 2b. High-Efficiency Operating Configuration for VBATT < 6.5V

Configuration 3: High Efficiency, 11V, VBATT < 6.5V In this configuration, N/E is driven high by LBO when VIN > 6.5V (Figure 2b). When VIN < VOUT, the IC boosts, and the linear regulator operates as a switch, with minimum forward drop. When VIN > VOUT, linear regulation begins. When V_{IN} > 6.5V (set by R5 and R6), the linear regulator forces a minimum forward drop of V_{FV} (typically 0.5V at 5V V_{OUT}) as LBO drives N/E high. This transition is not seen at the output, since the linear regulator already has an input-output voltage difference of 6.5V - 5V. Efficiency with VIN slightly higher than VOUT is equal to that of configuration 1, so configuration 3 is most suitable when the battery voltage may be near VOUT. This hookup has no functional shortcomings compared with configuration 2, except that two additional resistors (R5 and R6) are needed.

Configuration 4: Low Noise

With N/ \overline{E} connected to PS, when the IC is boosting, the linear regulator operates with VFV forward voltage (typically 0.5V at 5V VOUT) for optimum noise rejection. Linear regulation occurs when VIN > VOUT + VFV. The VFV voltage differential results in boost efficiency typically 10% lower than with the high-efficiency configurations.

ILIM

The current-limit-select input, ILIM, selects between the two peak current limits: 1.5A (ILIM = GND) and 0.8A (ILIM = PS). If the application requires 200mA or less from the MAX710/MAX711, select 0.8A. The lower peak current limit permits the use of smaller, low-cost inductors. The ILIM input is internally diode clamped to GND and PS, and should not be connected to signals outside this range.

Shutdown and Standby Modes

Grounding SHDN turns off the MAX710/MAX711 completely, disconnecting the input from the output. Tie SHDN to PS for normal operation.

The MAX710/MAX711 have a standby mode that shuts down the step-up converter. The linear regulator remains on with a 7μ A (typ) LDO quiescent current. Connect \overline{STBY} to ground to enter standby mode; otherwise, connect \overline{STBY} to PS.

Design Procedure

Output Voltage Selection

For the MAX710, you can obtain a 3.3V or 5V output voltage by tying 3/5 to GND or PS. Efficiency is typically 85% over a 2mA to 250mA load range. The device is bootstrapped, with power derived from the step-up voltage output (at PS). Under all load conditions, the

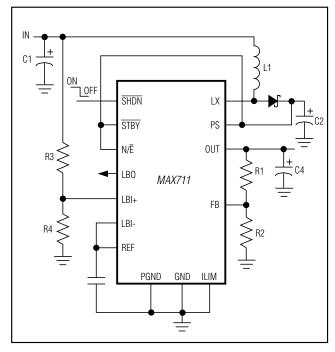


Figure 3. MAX711 Adjustable Output Voltage

MAX710/MAX711 typically start up with a 1V input. If the battery voltage exceeds the programmed output voltage, the output will linear regulate down to the selected output voltage.

The MAX711's adjustable output voltage is set by two resistors, R1 and R2 (Figure 3), which form a voltage divider between the output and FB. Use the following equation to determine the resistor values:

$$R1 = R2 [(VOUT / VREF) - 1]$$

where $V_{REF} = 1.25V$.

Since the input bias current at FB has a maximum value of 50nA, R1 and R2 can be large with no significant accuracy loss. Choose R2 in the $100k\Omega$ to $1M\Omega$ range and calculate R1 using the formula above. For 1% error, the current through R1 should be at least 100 times FB's bias current.

Low-Battery Comparator

The MAX710/MAX711 contain a comparator for low-battery detection. If the voltage at LBI+ falls below that at LBI- (typically connected to REF), LBO goes low. Hysteresis is typically 50mV. Set the low-battery monitor's threshold with two resistors, R3 and R4 (Figure 2), using the following equation:

$$R3 = R4 [(V_{LBT} / V_{LBI}) - 1]$$

Table 2. Component Selection

INDUCTORS (L1)	CAPACITORS	RECTIFIERS (D1)	
Sumida CD75-220 (1.5A), CDRH-74-220 (1.23A), or CD54-220	100μF, 16V low-ESR tantalum capacitor AVX TPSE107M016R0100 or Sprague 593D107X0016E2W	Schottky diode Motorola MBRS130T3	
Coilcraft DO33-08P-223	4.7µF, 16V tantalum capacitor Sprague 595D475X0016A2T		

where V_{LBT} is the desired threshold of the low-battery detector and V_{LBI}- is the voltage applied to the inverting input of the low-battery comparator. Since LBI current is less than 50nA, R3 and R4 can be large (typically 100k Ω to 1M Ω), minimizing input supply loading. If the low-battery comparator is not used, connect LBI+ to PS and LBI- to REF, leaving LBO unconnected.

Inductor Selection

A 22µH inductor value performs well in most MAX710/MAX711 applications. The inductance value is not critical, however, since the MAX710/MAX711 work with inductors in the 18µH to 100µH range. Smaller inductance values typically offer a smaller size for a given series resistance, allowing the smallest overall circuit dimensions. Circuits using larger inductance values exhibit higher output current capability and larger physical dimensions for a given series resistance. The inductor's incremental saturation current rating should be greater than the peak switch-current limit, which is 1.5A for ILIM = GND and 0.8A for ILIM = PS. However, it is generally acceptable to bias most inductors into saturation by as much as 20%, although this slightly reduces efficiency. The inductor's DC resistance significantly affects efficiency. See Tables 2 and 3 for a list of suggested inductors and suppliers.

Capacitor Selection

A 100 μ F, 16V, 0.1 Ω equivalent series resistance (ESR), surface-mount tantalum (SMT) output filter capacitor, C2, typically exhibits 50mV output ripple when stepping up from 2V to 5V at 100mA. Smaller capacitors (down to 10 μ F with higher ESRs) are acceptable for light loads or in applications that can tolerate higher output ripple. The ESR of both bypass and filter capacitors affects efficiency and output ripple. Output voltage ripple is the product of the peak inductor current and the output capacitor's ESR. Use low-ESR capacitors for best performance, or connect two or more filter capacitors in parallel. Low-ESR, SMT capacitors are currently available from Sprague (595D series) and AVX (TPS series). Sanyo OS-CON organic-semiconductor through-hole capacitors also exhibit very low ESR and are especially

useful for operation at cold temperatures. The output capacitor, C3, needs to be only 4.7µF to maintain linear regulator stability. See Tables 2 and 3 for a list of suggested capacitors and suppliers.

Rectifier Diode

For optimum performance, use a switching Schottky diode. Refer to Tables 2 and 3 for the suggested diode and supplier.

Applications Information

The MAX710/MAX711 high-frequency operation makes PC layout important for minimizing ground bounce and noise. Keep the IC's GND pin and the ground leads of C1 and C2 (Figure 1) less than 0.2in. (5mm) apart. Also keep all connections to the FB and LX pins as short as possible. To maximize output power and efficiency and minimize output ripple voltage, use a ground plane and solder the IC's GND pin directly to the ground plane.

Table 3. Component Suppliers

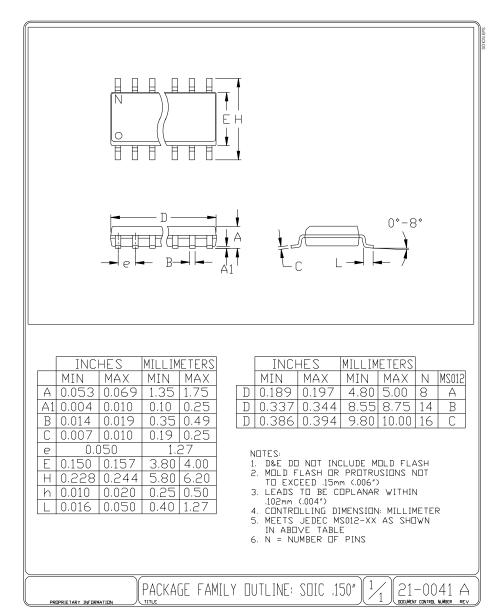
SUPPLIER	PHONE	FAX	
AVX	(803) 946-0690	(803) 626-3123	
Coilcraft	(847) 639-6400	(847) 639-1469	
Motorola	(602) 303-5454	(602) 994-6430	
Sanyo	(619) 661-6835	(619) 661-1055	
Sprague	(603) 224-1961	(603) 224-1430	
Sumida	(847) 956-0666	(847) 956-0702	

Chip Information

TRANSISTOR COUNT: 661

SUBSTRATE CONNECTED TO GND

Package Information



NOTES



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.

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